

# SMD Power Inductor

FMIM252012AV-Series(G)

## 1. Features

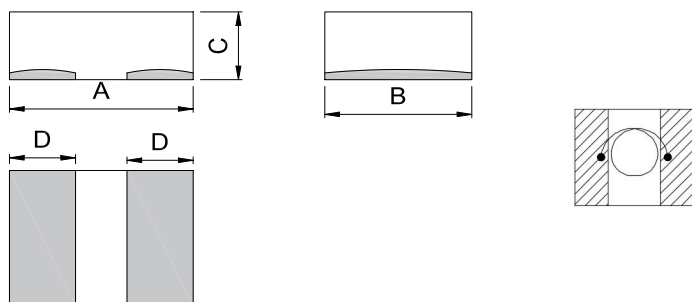
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.
5. High reliability -Reliability test complied to AEC-Q200.



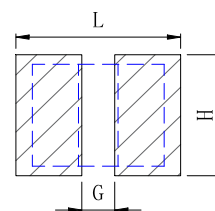
## 2. Applications

Automotive applications.

## 3. Dimensions



### Recommend PC Board Pattern

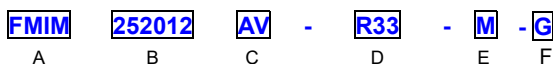


Series	A(mm)	B(mm)	C(mm)	D(mm)
FMIM252012A	2.5±0.3	2.0±0.3	1.0±0.2	0.9±0.3

L(mm)	G(mm)	H(mm)
2.9	0.5	2.3

Note: 1.PCB layout is referred to standard IPC-7351B  
 2. The above PCB layout reference only.  
 3. Recommend solder paste thickness at 0.10mm and above.

## 4. Part Numbering



- A: Series
- B: Dimension                      AxBxC
- C: Material
- D: Inductance                      R33=0.33uH
- E: Inductance Tolerance        M=±20%
- F: Coating                            Anti-static packaging

## 5. Specification

Part Number	Inductance L0 A( $\mu$ H) $\pm 20\%$	I rms ( A )		I sat ( A )		DCR ( m $\Omega$ )		Q (Min)	SRF (MHz) Ref	Impulse Voltage
		Typ	Max	Typ	Max	Typ	Max			
FMIM252012AV-R24MG	0.24	7.3	6.8	7.8	7.2	11.0	13.2	5	172	25V
FMIM252012AV-R33MG	0.33	6.8	6.3	7.5	6.8	14.0	17.0	5	165	25V
FMIM252012AV-R47MG	0.47	6.2	5.6	6.2	5.6	15.0	18.0	5	112	25V
FMIM252012AV-R68MG	0.68	5.3	4.9	5.5	5.0	23.0	27.6	5	90	25V
FMIM252012AV-1R0MG	1.00	4.5	4.2	5.0	4.2	33.0	39.6	5	63	25V
FMIM252012AV-1R5MG	1.50	3.7	3.4	4.0	3.5	43.0	51.6	5	55	25V
FMIM252012AV-2R2MG	2.20	3.1	2.8	3.4	3.1	66.0	79.2	5	45	25V
FMIM252012AV-3R3MG	3.30	2.4	2.2	3.0	2.7	115	138	5	30	25V
FMIM252012AV-4R7MG	4.70	2.0	1.8	2.8	2.5	170	204	5	23	25V

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25 $^{\circ}$ C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately  $\Delta T$  of 40 $^{\circ}$ C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 150 $^{\circ}$ C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.
9. Rated voltage 25V DC. The application of voltage depends on many factors. Over voltage may cause components failure、high temperature、and burn-out. User needs to verify for appropriate usage

### 10. Typical Performance Curves

